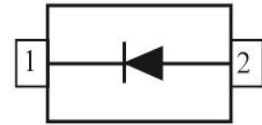
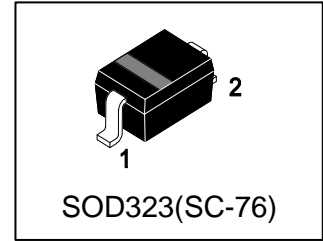


LUDZS9.1BT1G

S-LUDZS9.1BT1G

Zener Voltage Regulators
200 mW SOD-323 Surface Mount



1. FEATURES

- We declare that the material of product compliance with RoHS requirements and Halogen Free.
- S- prefix for automotive and other applications requiring unique site and control change requirements; AEC-Q101 qualified and PPAP capable.
- Silicon epitaxial planar

2. DEVICE MARKING AND ORDERING INFORMATION

Device	Marking	Shipping
LUDZS9.1BT1G	L2	3000/Tape&Reel
LUDZS9.1BT3G	L2	10000/Tape&Reel

3. MAXIMUM RATINGS (Ta = 25°C)

Parameter	Symbol	Limits	Unit
Total Device Dissipation, FR-5 Board (Note 1) @ TA = 25°C Derate above 25°C	PD	200 1.57	mW mW/°C
Thermal Resistance, Junction-to-Ambient(Note 1)	RθJA	635	°C/W
Junction and Storage temperature	TJ,Tstg	-55~+150	°C

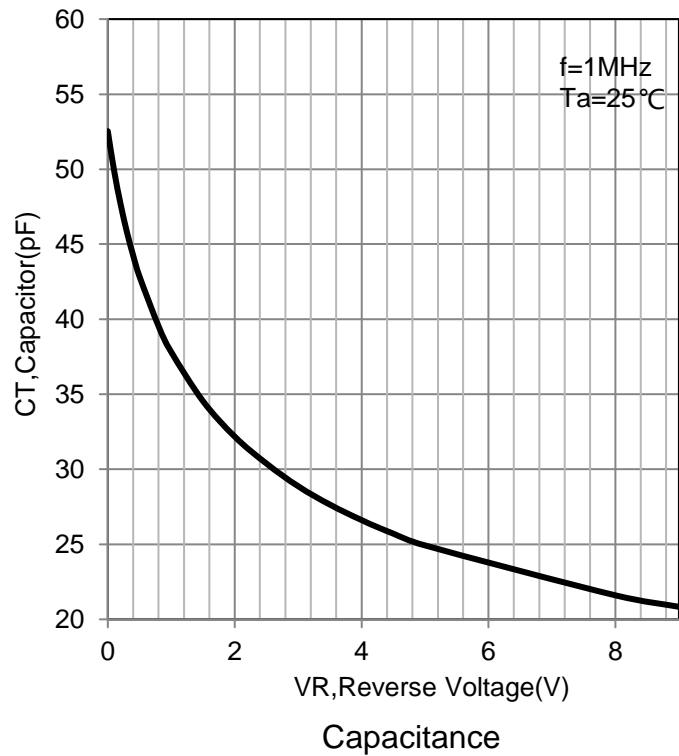
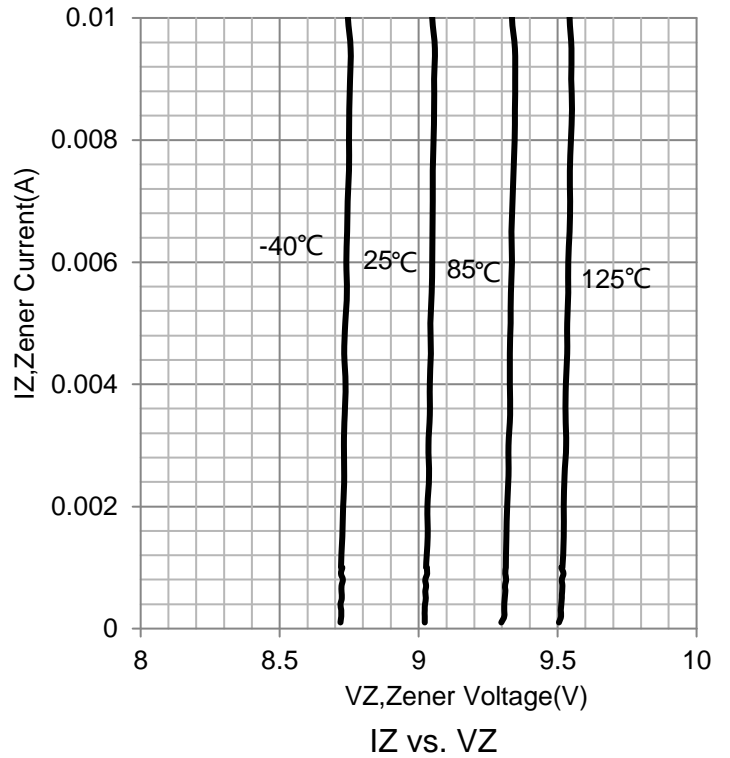
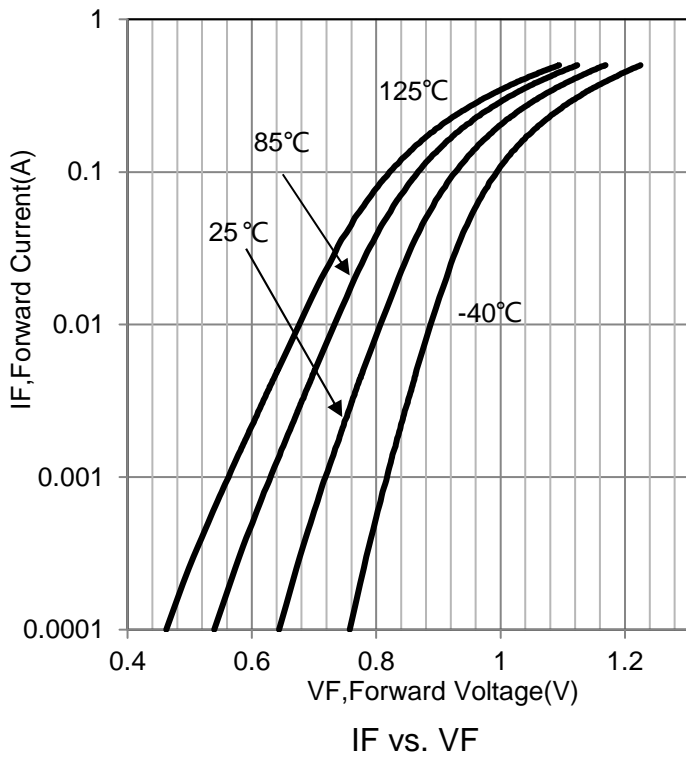
4. ELECTRICAL CHARACTERISTICS (Ta= 25°C)

Characteristic	Symbol	Min.	Typ.	Max.	Unit
Zener voltage (IZT=5mA)	VZ	8.85	-	9.23	V
Operating resistance (IZT=5mA)	ZZT	-	-	30	Ω
Rising operating resistance (IZK=0.5mA)	ZZK	-	-	60	Ω
Reverse current (VR=6V)	IR	-	-	0.5	μA

1. The Zener voltage (Vz) is measured 40ms after power is supplied.

2. The operating resistances (Zz , Zzk) are measured by superimposing a minute alternating current on the regulated current (Iz).

5.ELECTRICAL CHARACTERISTICS CURVES



6. OUTLINE AND DIMENSIONS

Notes:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.



DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.8	0.9	1	0.031	0.035	0.04
A1	0	0.05	0.1	0	0.002	0.004
A3	0.15REF			0.006REF		
b	0.25	0.32	0.4	0.01	0.012	0.016
C	0.089	0.12	0.177	0.003	0.005	0.007
D	1.6	1.7	1.8	0.062	0.066	0.07
E	1.15	1.25	1.35	0.045	0.049	0.053
L	0.08			0.003		
HE	2.3	2.5	2.7	0.09	0.098	0.105

7. SOLDERING FOOTPRINT

